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C 1. (Amended) A manufacturing method for manufacturing an electro-optical device having an electro-optical panel with a substrate holding an electro-optical material and a mount base member bonded to the substrate, the manufacturing method comprising:

a 1 a step of connecting a first terminal bank, formed on the surface of the substrate, to a second terminal bank formed on the surface of the mount base member, the second terminal bank being at a pitch different from a pitch of the first terminal bank when the substrate is bonded to the mount base member,

wherein the connection step connects the first terminal bank and the second terminal bank such that the pitch of the first terminal bank and the pitch of the second terminal bank become substantially equal to each other when the substrate and the mount base member are deformed during the bonding of the substrate and the mount base member.

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C 9. (Amended) A terminal connection method for connecting a first terminal bank formed on the surface of a first base member to a second terminal bank formed on the surface of a second base member, the connection method comprising the steps of:

a 2 fabricating the second terminal bank at a pitch different from a pitch of the first terminal bank;

connecting the first terminal bank and the second terminal bank;

bonding the first base member to the second base member; and

during the bonding step, deforming the first base member and the second base member such that the pitch of the first terminal bank and the pitch of the second terminal bank become substantially equal.

12. (Amended) A manufacturing method for manufacturing a mount base member having a second terminal bank to be connected to a first terminal bank formed on a base member and being thermal-compression bonded to the base member, the manufacturing method comprising:

the step of forming the second terminal bank in such a manner that the pitch of the second terminal bank is a/b times the pitch of the first terminal bank;

wherein subsequent to the thermal compression bonding of the mount base member to the base member, the first terminal bank expands in width in the transverse direction thereof on the base member by a times and the second terminal bank expands in width in the transverse direction thereof on the mount base member by b times.

24. (Amended) A mount base member to be thermal compression bonded to a substrate of an electro-optical panel, the mount base member comprising:

a second terminal bank to be connected to a first terminal bank formed on the substrate;

wherein the pitch of the second terminal bank prior to the thermal compression bonding is a/b times the pitch of the first terminal bank; and

wherein subsequent to the thermal compression bonding of the mount base member to the substrate, the first terminal bank expands in width in the transverse direction thereof on the substrate by a times and the second terminal bank expands in width in the transverse direction thereof on the mount base member by b times.

25. (Amended) A mount base member to be thermal compression bonded to a substrate of an electro-optical panel, the mount base member comprising;

a second terminal bank to be connected to a first terminal bank formed on the substrate;

wherein the pitch of the second terminal bank prior to the thermal compression bonding is $1/b$ times the pitch of the first terminal bank; and

wherein subsequent to the thermal compression bonding of the mount base member to the substrate, the second terminal bank expands in width in the transverse direction thereof on the mount base member by b times.
